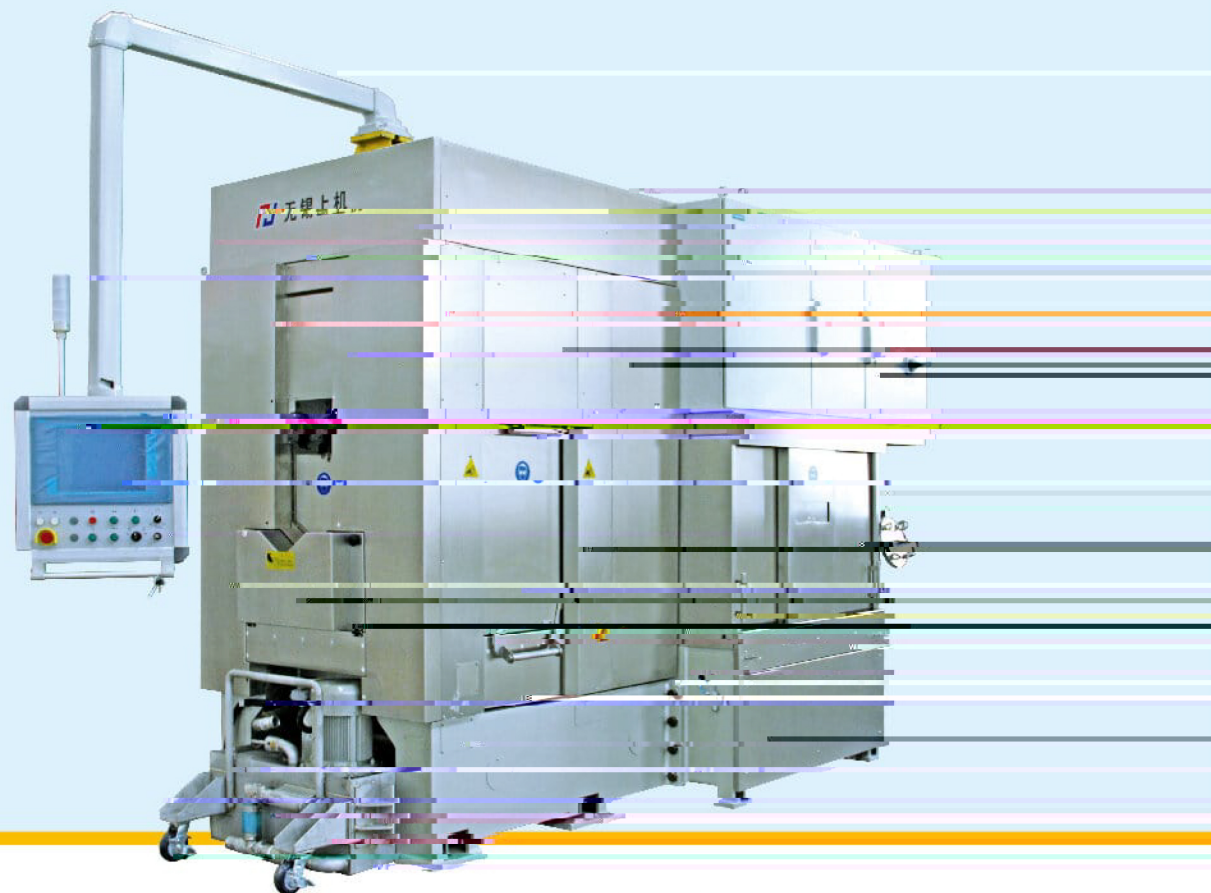


# WSK060 蓝宝石切片机

WSK060 Sapphire Slicing Machine



## 技术规格参数 Specifications and Technical Parameters

规格 Specification	英寸 (inch)
长度 Length	800mm
厚度 Thickness	>0.2mm

### 主要参数 Main Parameters

导轮直径 Guide wheel diameter	220mm
导轮轴距 Guide wheel base	440mm
导轮长度 Guide wheel length	300mm
线速度 Wire speed	200m/min
切割速度 Cutting speed	1000mm/min
摇摆角度 Swinging angle	±12°
切割方向 Cutting direction	前进或后退双向切割
存储线盘 Storage wire wheels	>200个
水箱容量 Water tank capacity	120L

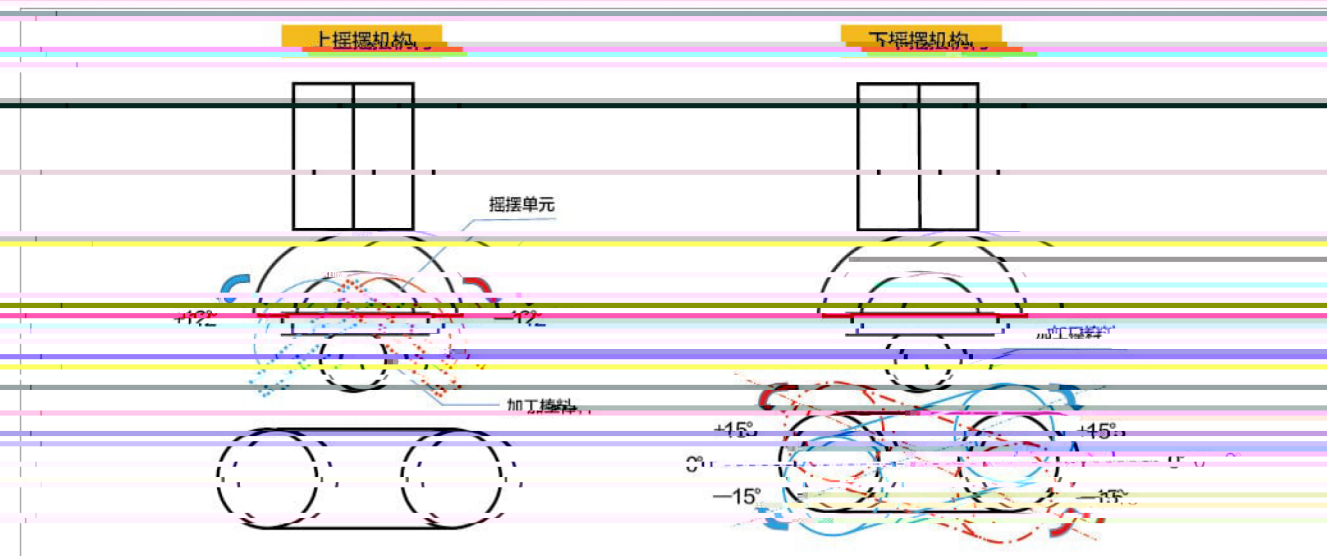
### 能源供给 Power supply

电源连接 Power connection	220/380V, 3PH, 50HZ
平均功率 Average power	35KW
冷却水源 Cooling water	10~17°C

### 外形尺寸 Outline size

机床外形尺寸 (长*宽*高) Equipment size (L*W*H)	1900*2100*2500mm
机床重量 weight	≈ 12000kg

### 示意图 sketch



## 设备用途与性能特征

- 本机床用于自动切割各种坚硬易脆材料，如硅、锗、石英玻璃、陶瓷、蓝宝石晶体等。
- 机床所有电器元件均采用国际国内知名品牌，保证机床的稳定性。
- 采用西门子公司技术的集成化PC机，15寸触摸屏。
- 电控柜配备独立温控系统，保证各控制元件正常工作。
- 设备具备摇摆功能，双支撑摇摆单元优化了金刚石切割蓝宝石的性能，缩短了切割时间，并提高了晶片的质量。
- 滑轮数量最少化设计（仅6个滑轮），减少刚线扭曲和疲劳。

## Application and Features

- This machine can be used to automatically cut hard and brittle materials, using diamond tools to cut silicon, germanium, quartz glass, ceramics, sapphire crystals, etc.
- All electrical components apply international and domestic outstanding brands to ensure the stability of the machine.
- Apply integrated PC or SIEMENS simotion controlling system, 15" touch screen.
- The electric control cabinet is equipped with independent temperature control system to ensure the normal operation of each control component.
- The equipment features swinging function, and the dual support swinging function unit optimizes the performance of diamond wire-cut sapphire, shortens the cutting time, and improves the wafer quality.
- Minimal design number of pulleys (only 6 pulleys), to reduce wire distortion and fatigue.